

LNPT™ COLORCOMP™ COMPOUND EX10304C

DESCRIPTION

LNP COLORCOMP EX10304C compound is based on unfilled Polyetherimide (PEI) resin. Added features of this grade include: LNP Clean Compounding Technology.

GENERAL INFORMATION	
Features	Aesthetics/Visual effects, Low ionics/Outgassing/Liquid particle count, High temperature resistance, No PFAS intentionally added
Fillers	Unreinforced
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

Revision 20241024

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yld, Type I, 5 mm/min	106	MPa	ASTM D638
Tensile Stress, brk, Type I, 5 mm/min	95	MPa	ASTM D638
Tensile Strain, yld, Type I, 5 mm/min	7	%	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	60	%	ASTM D638
Tensile Modulus, 5 mm/min	3290	MPa	ASTM D638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	160	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	3020	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	1335	J/m	ASTM D4812
Izod Impact, notched, 23°C	34	J/m	ASTM D256
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 6.4 mm, unannealed	200	°C	ASTM D648
Relative Temp Index, Elec ⁽²⁾	105	°C	UL 746B
Relative Temp Index, Mech w/impact ⁽²⁾	105	°C	UL 746B
Relative Temp Index, Mech w/o impact ⁽²⁾	105	°C	UL 746B
PHYSICAL ⁽¹⁾			
Density	1.27	g/cm ³	ASTM D792
Mold Shrinkage, flow, 24 hrs ⁽³⁾	0.5 – 0.7	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽³⁾	0.5 – 0.7	%	ASTM D955
FLAME CHARACTERISTICS ⁽²⁾			
UL Yellow Card Link	E207780-101339191	-	-
UL Recognized, 94V-2 Flame Class Rating	≥0.8	mm	UL 94

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
INJECTION MOLDING ⁽⁴⁾			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	360 – 400	°C	
Rear - Zone 1 Temperature	360 – 380	°C	
Middle - Zone 2 Temperature	370 – 390	°C	
Front - Zone 3 Temperature	380 – 400	°C	
Nozzle Temperature	390 – 400	°C	
Mold Temperature	140 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw speed (Circumferential speed)	0.2 – 0.3	m/s	
Vent Depth	0.025 – 0.076	mm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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